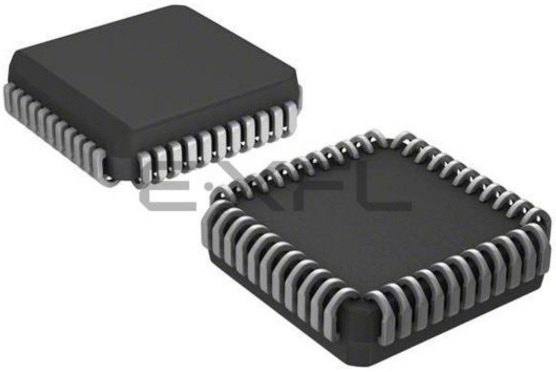


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

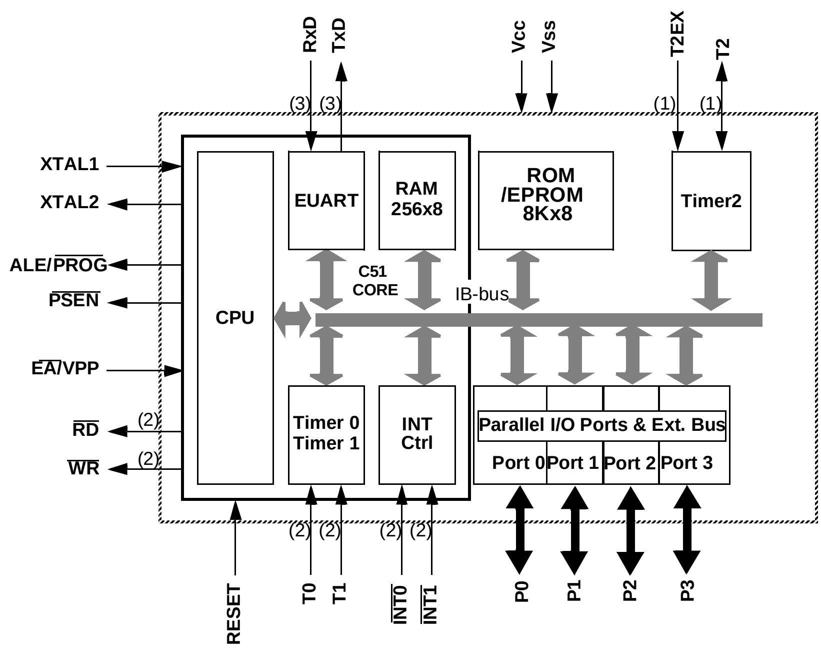
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	80C51
Core Size	8-Bit
Speed	60/30MHz
Connectivity	UART/USART
Peripherals	POR
Number of I/O	32
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.6x16.6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ts80c32x2-vib

Table 1. Memory Size

	ROM (bytes)	EPROM (bytes)	TOTAL RAM (bytes)
TS80C32X2	0	0	256
TS80C52X2	8k	0	256
TS87C52X2	0	8k	256

Block Diagram



Notes: 1. Alternate function of Port 1
2. Alternate function of Port 3

Mnemonic	Pin Number			Type	Name and Function
	DIL	LCC	VQFP 1.4		
V_{SS}	20	22	16	I	**Ground:** 0V reference
Vss1		1	39	I	Optional Ground: **Contact the Sales Office for ground connection.**
V_{CC}	40	44	38	I	**Power Supply:** This is the power supply voltage for normal, idle and power-down operation
P0.0-P0.7	39-32	43-36	37-30	I/O	**Port 0**: Port 0 is an open-drain, bidirectional I/O port. Port 0 pins that have 1s written to them float and can be used as high impedance inputs.Port 0 pins must be polarized to Vcc or Vss in order to prevent any parasitic current consumption. Port 0 is also the multiplexed low-order address and data bus during access to external program and data memory. In this application, it uses strong internal pull-up when emitting 1s. Port 0 also inputs the code bytes during EPROM programming. External pull-ups are required during program verification during which P0 outputs the code bytes.
P1.0-P1.7	1-8	2-9	40-44 1-3	I/O	Port 1: Port 1 is an 8-bit bidirectional I/O port with internal pull-ups. Port 1 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 1 pins that are externally pulled low will source current because of the internal pull-ups. Port 1 also receives the low-order address byte during memory programming and verification. Alternate functions for Port 1 include:
	1	2	40	I/O	**T2 (P1.0):** Timer/Counter 2 external count input/Clockout
	2	3	41	I	**T2EX (P1.1):** Timer/Counter 2 Reload/Capture/Direction Control
P2.0-P2.7	21-28	24-31	18-25	I/O	**Port 2**: Port 2 is an 8-bit bidirectional I/O port with internal pull-ups. Port 2 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 2 pins that are externally pulled low will source current because of the internal pull-ups. Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX atDPTR).In this application, it uses strong internal pull-ups emitting 1s. During accesses to external data memory that use 8-bit addresses (MOVX atRi), port 2 emits the contents of the P2 SFR. Some Port 2 pins receive the high order address bits during EPROM programming and verification: P2.0 to P2.4
P3.0-P3.7	10-17	11, 13-19	5, 7-13	I/O	Port 3: Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. Port 3 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 3 pins that are externally pulled low will source current because of the internal pull-ups. Port 3 also serves the special features of the 80C51 family, as listed below.
	10	11	5	I	**RXD (P3.0):** Serial input port
	11	13	7	O	**TXD (P3.1):** Serial output port
	12	14	8	I	**$\overline{\text{INT0}}$ (P3.2):** External interrupt 0

TS80C52X2 Enhanced Features

In comparison to the original 80C52, the TS80C52X2 implements some new features, which are:

- The X2 option
- The Dual Data Pointer
- The 4 level interrupt priority system
- The power-off flag
- The ONCE mode
- The ALE disabling
- Some enhanced features are also located in the UART and the Timer 2

X2 Feature

The TS80C52X2 core needs only 6 clock periods per machine cycle. This feature called ”X2” provides the following advantages:

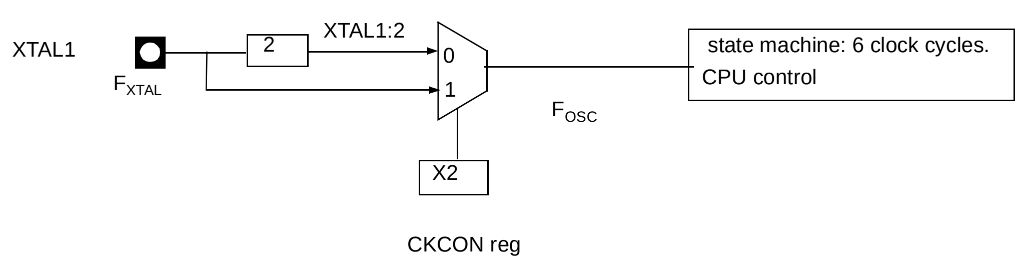
- Divide frequency crystals by 2 (cheaper crystals) while keeping same CPU power
- Save power consumption while keeping same CPU power (oscillator power saving)
- Save power consumption by dividing dynamically operating frequency by 2 in operating and idle modes
- Increase CPU power by 2 while keeping same crystal frequency

In order to keep the original C51 compatibility, a divider by 2 is inserted between the XTAL1 signal and the main clock input of the core (phase generator). This divider may be disabled by software.

Description

The clock for the whole circuit and peripheral is first divided by two before being used by the CPU core and peripherals. This allows any cyclic ratio to be accepted on XTAL1 input. In X2 mode, as this divider is bypassed, the signals on XTAL1 must have a cyclic ratio between 40 to 60%. Figure 1. shows the clock generation block diagram. X2 bit is validated on XTAL1÷2 rising edge to avoid glitches when switching from X2 to STD mode. Figure 2 shows the mode switching waveforms.

Figure 1. Clock Generation Diagram



Dual Data Pointer Register (Ddptr)

The additional data pointer can be used to speed up code execution and reduce code size in a number of ways.

The dual DPTR structure is a way by which the chip will specify the address of an external data memory location. There are two 16-bit DPTR registers that address the external memory, and a single bit called
DPS = AUXR1/bit0 (See Table 5.) that allows the program code to switch between them (Refer to Figure 3).

Figure 3. Use of Dual Pointer

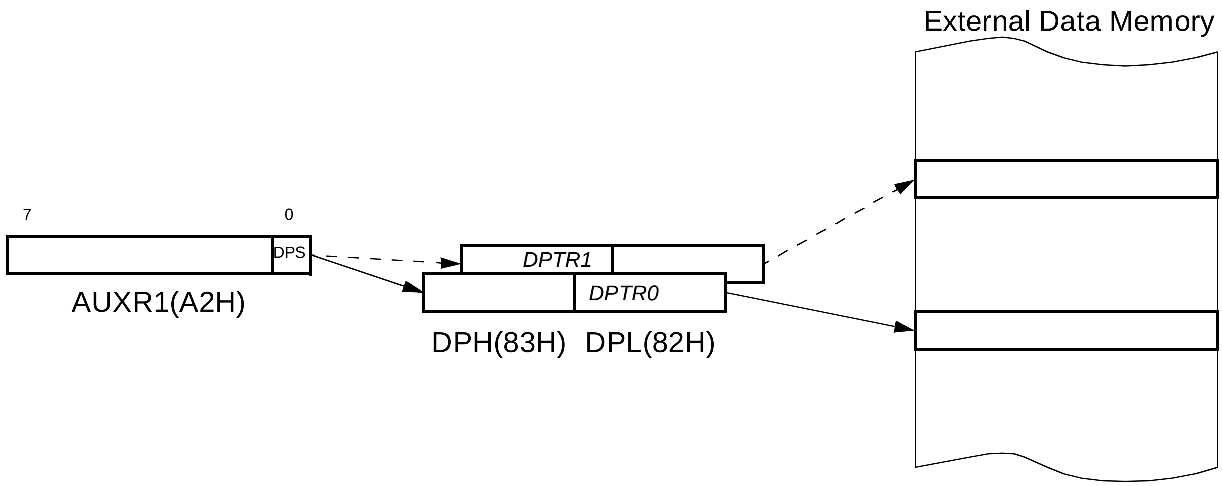


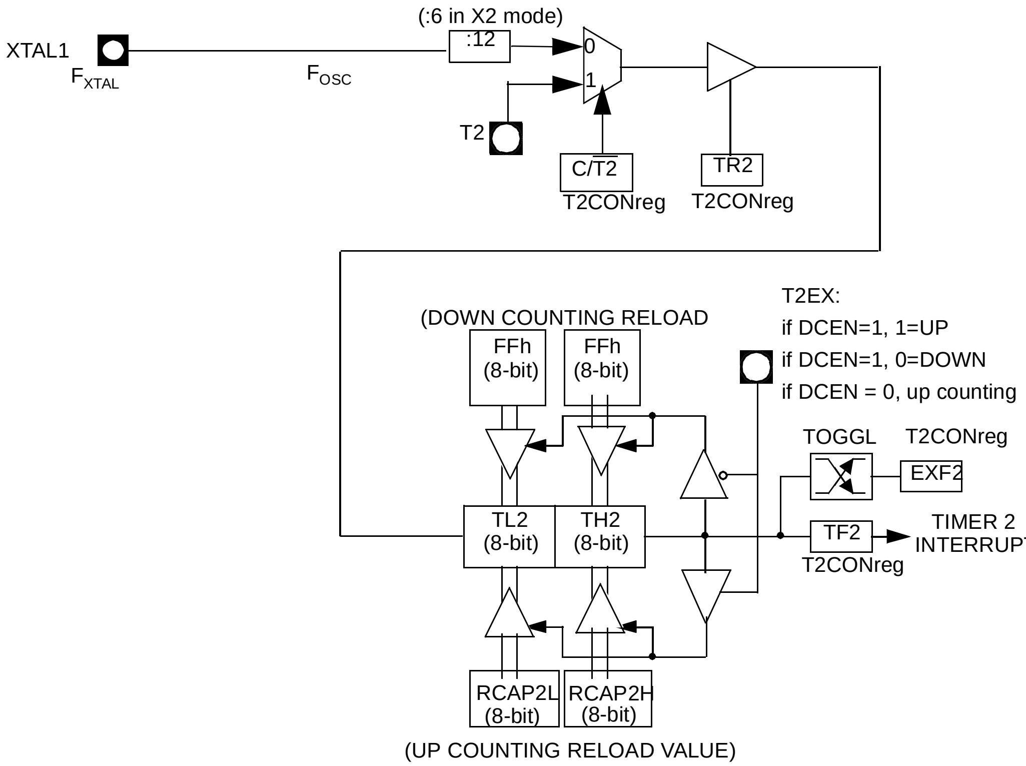
Table 4. AUXR1: Auxiliary Register 1

7	6	5	4	3	2	1	0
-	-	-	-	GF3	0	-	DPS

Bit Number	Bit Mnemonic	Description
7	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
6	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
5	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
4	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
3	GF3	This bit is a general purpose user flag
2	0	**Reserved** Always stuck at 0
1	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
0	DPS	**Data Pointer Selection** Clear to select DPTR0. Set to select DPTR1.

Reset Value = XXXX XXX0
Not bit addressable

Figure 4. Auto-reload Mode Up/Down Counter (DCEN = 1)



Programmable Clock-output

In the clock-out mode, timer 2 operates as a 50%-duty-cycle, programmable clock generator (See Figure 5) . The input clock increments TL2 at frequency $F_{OSC}/2$. The timer repeatedly counts to overflow from a loaded value. At overflow, the contents of RCAP2H and RCAP2L registers are loaded into TH2 and TL2. In this mode, timer 2 overflows do not generate interrupts. The formula gives the clock-out frequency as a function of the system oscillator frequency and the value in the RCAP2H and RCAP2L registers :

$$Clock-OutFrequency = \frac{F_{osc}}{4 \times (65536 - RCAP2H/RCAP2L)}$$

For a 16 MHz system clock, timer 2 has a programmable frequency range of 61 Hz ($F_{OSC}/2^{16}$) to 4 MHz ($F_{OSC}/4$). The generated clock signal is brought out to T2 pin (P1.0).

Timer 2 is programmed for the clock-out mode as follows:

- Set T2OE bit in T2MOD register.
- Clear C/$\overline{T2}$ bit in T2CON register.
- Determine the 16-bit reload value from the formula and enter it in RCAP2H/RCAP2L registers.
- Enter a 16-bit initial value in timer registers TH2/TL2. It can be the same as the reload value or a different one depending on the application.
- To start the timer, set TR2 run control bit in T2CON register.

It is possible to use timer 2 as a baud rate generator and a clock generator simultaneously. For this configuration, the baud rates and clock frequencies are not independent since both functions use the values in the RCAP2H and RCAP2L registers.

Table 5. T2CON Register

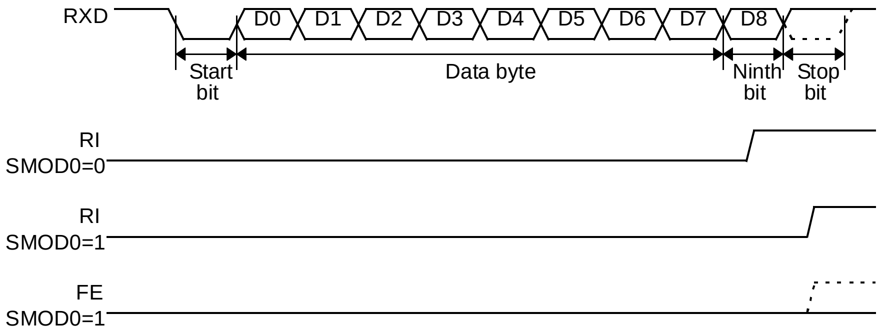
T2CON - Timer 2 Control Register (C8h)

7	6	5	4	3	2	1	0
TF2	**EXF2**	**RCLK**	**TCLK**	**EXEN2**	**TR2**	**C/T2#**	**CP/RL2#**

Bit Number	Bit Mnemonic	Description
7	TF2	**Timer 2 overflow Flag** Must be cleared by software. Set by hardware on timer 2 overflow, if RCLK = 0 and TCLK = 0.
6	EXF2	**Timer 2 External Flag** Set when a capture or a reload is caused by a negative transition on T2EX pin if EXEN2=1. When set, causes the CPU to vector to timer 2 interrupt routine when timer 2 interrupt is enabled. Must be cleared by software. EXF2 doesn't cause an interrupt in Up/down counter mode (DCEN = 1)
5	RCLK	**Receive Clock bit** Clear to use timer 1 overflow as receive clock for serial port in mode 1 or 3. Set to use timer 2 overflow as receive clock for serial port in mode 1 or 3.
4	TCLK	**Transmit Clock bit** Clear to use timer 1 overflow as transmit clock for serial port in mode 1 or 3. Set to use timer 2 overflow as transmit clock for serial port in mode 1 or 3.
3	EXEN2	**Timer 2 External Enable bit** Clear to ignore events on T2EX pin for timer 2 operation. Set to cause a capture or reload when a negative transition on T2EX pin is detected, if timer 2 is not used to clock the serial port.
2	TR2	**Timer 2 Run control bit** Clear to turn off timer 2. Set to turn on timer 2.
1	C/T2#	**Timer/Counter 2 select bit** Clear for timer operation (input from internal clock system: F_{OSC}). Set for counter operation (input from T2 input pin, falling edge trigger). Must be 0 for clock out mode.
0	CP/RL2#	**Timer 2 Capture/Reload bit** If RCLK=1 or TCLK=1, CP/RL2# is ignored and timer is forced to Auto-reload on timer 2 overflow. Clear to Auto-reload on timer 2 overflows or negative transitions on T2EX pin if EXEN2=1. Set to capture on negative transitions on T2EX pin if EXEN2=1.

Reset Value = 0000 0000b
Bit addressable

Figure 8. UART Timings in Modes 2 and 3



Automatic Address Recognition

The automatic address recognition feature is enabled when the multiprocessor communication feature is enabled (SM2 bit in SCON register is set).

Implemented in hardware, automatic address recognition enhances the multiprocessor communication feature by allowing the serial port to examine the address of each incoming command frame. Only when the serial port recognizes its own address, the receiver sets RI bit in SCON register to generate an interrupt. This ensures that the CPU is not interrupted by command frames addressed to other devices.

If desired, you may enable the automatic address recognition feature in mode 1. In this configuration, the stop bit takes the place of the ninth data bit. Bit RI is set only when the received command frame address matches the device's address and is terminated by a valid stop bit.

To support automatic address recognition, a device is identified by a given address and a broadcast address.

Note: The multiprocessor communication and automatic address recognition features cannot be enabled in mode 0 (i.e. setting SM2 bit in SCON register in mode 0 has no effect).

Given Address

Each device has an individual address that is specified in SADDR register; the SADEN register is a mask byte that contains don't-care bits (defined by zeros) to form the device's given address. The don't-care bits provide the flexibility to address one or more slaves at a time. The following example illustrates how a given address is formed.

To address a device by its individual address, the SADEN mask byte must be `1111 1111b`.

For example:

```
SADDR0101 0110b
SADEN1111 1100b
Given0101 01XXb
```

The following is an example of how to use given addresses to address different slaves:

```
Slave A:SADDR1111 0001b
        SADEN1111 1010b
        Given1111 0X0Xb

Slave B:SADDR1111 0011b
        SADEN1111 1001b
        Given1111 0XX1b

Slave C:SADDR1111 0010b
        SADEN1111 1101b
        Given1111 00X1b
```

The SADEN byte is selected so that each slave may be addressed separately.

For slave A, bit 0 (the LSB) is a don't-care bit; for slaves B and C, bit 0 is a 1. To communicate with slave A only, the master must send an address where bit 0 is clear (e.g.

1111 0000b).
For slave A, bit 1 is a 1; for slaves B and C, bit 1 is a don't care bit. To communicate with slaves B and C, but not slave A, the master must send an address with bits 0 and 1 both set (e.g. 1111 0011b).
To communicate with slaves A, B and C, the master must send an address with bit 0 set, bit 1 clear, and bit 2 clear (e.g. 1111 0001b).

Broadcast Address

A broadcast address is formed from the logical OR of the SADDR and SADEN registers with zeros defined as don't-care bits, e.g.:

```
SADDR 0101 0110b
SADEN 1111 1100b
Broadcast =SADDR OR SADEN1111 111Xb
```

The use of don't-care bits provides flexibility in defining the broadcast address, however in most applications, a broadcast address is FFh. The following is an example of using broadcast addresses:

```
Slave A:SADDR1111 0001b
        SADEN1111 1010b
        Broadcast1111 1X11b,

Slave B:SADDR1111 0011b
        SADEN1111 1001b
        Broadcast1111 1X11B,

Slave C:SADDR=1111 0010b
        SADEN1111 1101b
        Broadcast1111 1111b
```

For slaves A and B, bit 2 is a don't care bit; for slave C, bit 2 is set. To communicate with all of the slaves, the master must send an address FFh. To communicate with slaves A and B, but not slave C, the master can send and address FBh.

Reset Addresses

On reset, the SADDR and SADEN registers are initialized to 00h, i.e. the given and broadcast addresses are XXXX XXXXb (all don't-care bits). This ensures that the serial port will reply to any address, and so, that it is backwards compatible with the 80C51 microcontrollers that do not support automatic address recognition.

Table 7. SADEN Register
SADEN - Slave Address Mask Register (B9h)

7	6	5	4	3	2	1	0

Reset Value = 0000 0000b
Not bit addressable

Table 8. SADDR Register
SADDR - Slave Address Register (A9h)

7	6	5	4	3	2	1	0

Reset Value = 0000 0000b
Not bit addressable

Table 10. PCON Register

PCON - Power Control Register (87h)

7	6	5	4	3	2	1	0
SMOD1	SMOD0	-	POF	GF1	GF0	PD	IDL

Bit Number	Bit Mnemonic	Description
7	SMOD1	**Serial port Mode bit 1** Set to select double baud rate in mode 1, 2 or 3.
6	SMOD0	**Serial port Mode bit 0** Clear to select SM0 bit in SCON register. Set to to select FE bit in SCON register.
5	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
4	POF	**Power-off Flag** Clear to recognize next reset type. Set by hardware when VCC rises from 0 to its nominal voltage. Can also be set by software.
3	GF1	**General purpose Flag** Cleared by user for general purpose usage. Set by user for general purpose usage.
2	GF0	**General purpose Flag** Cleared by user for general purpose usage. Set by user for general purpose usage.
1	PD	**Power-down mode bit** Cleared by hardware when reset occurs. Set to enter power-down mode.
0	IDL	**Idle mode bit** Clear by hardware when interrupt or reset occurs. Set to enter idle mode.

Reset Value = 00X1 0000b

Not bit addressable

Power-off flag reset value will be 1 only after a power on (cold reset). A warm reset doesn’t affect the value of this bit.

TS80C52X2

ROM Structure

The TS80C52X2 ROM memory is divided in three different arrays:

- the code array:8 Kbytes.
- the encryption array:64 bytes.
- the signature array:4 bytes.

ROM Lock System

The program Lock system, when programmed, protects the on-chip program against software piracy.

Encryption Array

Within the ROM array are 64 bytes of encryption array that are initially unprogrammed (all FF's). Every time a byte is addressed during program verify, 6 address lines are used to select a byte of the encryption array. This byte is then exclusive-NOR'ed (XNOR) with the code byte, creating an encrypted verify byte. The algorithm, with the encryption array in the unprogrammed state, will return the code in its original, unmodified form.

When using the encryption array, one important factor needs to be considered. If a byte has the value FFh, verifying the byte will produce the encryption byte value. If a large block (>64 bytes) of code is left unprogrammed, a verification routine will display the content of the encryption array. For this reason all the unused code bytes should be programmed with random values. This will ensure program protection.

Program Lock Bits

The lock bits when programmed according to Table 19. will provide different level of protection for the on-chip code and data.

Table 19. Program Lock bits

Program Lock Bits				
Security level	**LB1**	**LB2**	**LB3**	**Protection Description**
1	U	U	U	No program lock features enabled. Code verify will still be encrypted by the encryption array if programmed. MOVC instruction executed from external program memory returns non encrypted data.
2	P	U	U	MOVC instruction executed from external program memory are disabled from fetching code bytes from internal memory, $\overline{EA}$ is sampled and latched on reset.

U: unprogrammed
P: programmed

Signature bytes

The TS80C52X2 contains 4 factory programmed signatures bytes. To read these bytes, perform the process described in section 9.

Verify Algorithm

Refer to Section "Verify Algorithm".

EPROM Structure

The TS87C52X2 is divided in two different arrays:

- the code array: 8 Kbytes
- the encryption array: 64 bytes

In addition a third non programmable array is implemented:

- the signature array: 4 bytes

EPROM Lock System

The program Lock system, when programmed, protects the on-chip program against software piracy.

Encryption Array

Within the EPROM array are 64 bytes of encryption array that are initially unprogrammed (all FF's). Every time a byte is addressed during program verify, 6 address lines are used to select a byte of the encryption array. This byte is then exclusive-NOR'ed (XNOR) with the code byte, creating an encrypted verify byte. The algorithm, with the encryption array in the unprogrammed state, will return the code in its original, unmodified form.

When using the encryption array, one important factor needs to be considered. If a byte has the value FFh, verifying the byte will produce the encryption byte value. If a large block (>64 bytes) of code is left unprogrammed, a verification routine will display the content of the encryption array. For this reason all the unused code bytes should be programmed with random values. This will ensure program protection.

Program Lock Bits

The three lock bits, when programmed according to Table 1., will provide different level of protection for the on-chip code and data.

Program Lock Bits				
Security level	LB1	LB2	LB3	Protection Description
1	U	U	U	No program lock features enabled. Code verify will still be encrypted by the encryption array if programmed. MOVC instruction executed from external program memory returns non encrypted data.
2	P	U	U	MOVC instruction executed from external program memory are disabled from fetching code bytes from internal memory, $\overline{EA}$ is sampled and latched on reset, and further programming of the EPROM is disabled.
3	U	P	U	Same as 2, also verify is disabled.
4	U	U	P	Same as 3, also external execution is disabled.

U: unprogrammed
P: programmed

WARNING: Security level 2 and 3 should only be programmed after EPROM and Core verification.

Signature Bytes

The TS80/87C52X2 contains 4 factory programmed signatures bytes. To read these bytes, perform the process described in section 9.

EPROM Programming

Set-up modes

In order to program and verify the EPROM or to read the signature bytes, the TS87C52X2 is placed in specific set-up modes (See Figure 11.).

Electrical Characteristics

Absolute Maximum Ratings[1]

Ambiant Temperature Under Bias:
C = commercial..0°C to 70°C
I = industrial ....-40°C to 85°C
Storage Temperature .... -65°C to + 150°C
Voltage on V_{CC} to V_{SS} ....-0.5V to + 7 V
Voltage on V_{PP} to V_{SS} ....-0.5V to + 13 V
Voltage on Any Pin to V_{SS}..........................-0.5V to V_{CC} + 0.5V
Power Dissipation .... 1 W[2]

Notes:
1. Stresses at or above those listed under " Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability.
2. This value is based on the maximum allowable die temperature and the thermal resistance of the package.

Power Consumption Measurement

Since the introduction of the first C51 devices, every manufacturer made operating Icc measurements under reset, which made sense for the designs were the CPU was running under reset. In Atmel new devices, the CPU is no more active during reset, so the power consumption is very low but is not really representative of what will happen in the customer system. That's why, while keeping measurements under Reset, Atmel presents a new way to measure the operating Icc:

Using an internal test ROM, the following code is executed:

Label: SJMP Label (80 FE)

Ports 1, 2, 3 are disconnected, Port 0 is tied to FFh, EA = Vcc, RST = Vss, XTAL2 is not connected and XTAL1 is driven by the clock.

This is much more representative of the real operating Icc.

DC Parameters for Standard Voltage

T_A = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 5V ± 10%; F = 0 to 40 MHz.
T_A = -40°C to +85°C; V_{SS} = 0 V; V_{CC} = 5V ± 10%; F = 0 to 40 MHz.

Table 22. DC Parameters in Standard Voltage

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V_{IL}	Input Low Voltage	-0.5		0.2 V_{CC} - 0.1	V	
V_{IH}	Input High Voltage except XTAL1, RST	0.2 V_{CC} + 0.9		V_{CC} + 0.5	V	
V_{IH1}	Input High Voltage, XTAL1, RST	0.7 V_{CC}		V_{CC} + 0.5	V	
V_{OL}	Output Low Voltage, ports 1, 2, 3 [6]			0.3 0.45 1.0	V V V	I_{OL} = 100 μA[4] I_{OL} = 1.6 mA[4] I_{OL} = 3.5 mA[4]
V_{OL1}	Output Low Voltage, port 0 [6]			0.3 0.45 1.0	V V V	I_{OL} = 200 μA[4] I_{OL} = 3.2 mA[4] I_{OL} = 7.0 mA[4]
V_{OL2}	Output Low Voltage, ALE, $\overline{PSEN}$			0.3 0.45 1.0	V V V	I_{OL} = 100 μA[4] I_{OL} = 1.6 mA[4] I_{OL} = 3.5 mA[4]

DC Parameters for Low Voltage

T_A = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 2.7 V to 5.5V ; F = 0 to 30 MHz.
T_A = -40°C to +85°C; V_{SS} = 0 V; V_{CC} = 2.7 V to 5.5V ; F = 0 to 30 MHz.

Table 23. DC Parameters for Low Voltage

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V_{IL}	Input Low Voltage	-0.5		0.2 V_{CC} - 0.1	V	
V_{IH}	Input High Voltage except XTAL1, RST	0.2 V_{CC} + 0.9		V_{CC} + 0.5	V	
V_{IH1}	Input High Voltage, XTAL1, RST	0.7 V_{CC}		V_{CC} + 0.5	V	
V_{OL}	Output Low Voltage, ports 1, 2, 3 [(6)]			0.45	V	I_{OL} = 0.8 mA[(4)]
V_{OL1}	Output Low Voltage, port 0, ALE, $\overline{PSEN}$ [(6)]			0.45	V	I_{OL} = 1.6 mA[(4)]
V_{OH}	Output High Voltage, ports 1, 2, 3	0.9 V_{CC}			V	I_{OH} = -10 µA
V_{OH1}	Output High Voltage, port 0, ALE, $\overline{PSEN}$	0.9 V_{CC}			V	I_{OH} = -40 µA
I_{IL}	Logical 0 Input Current ports 1, 2 and 3			-50	µA	Vin = 0.45V
I_{LI}	Input Leakage Current			±10	µA	0.45V < Vin < V_{CC}
I_{TL}	Logical 1 to 0 Transition Current, ports 1, 2, 3			-650	µA	Vin = 2.0 V
R_{RST}	RST Pulldown Resistor	50	90 [(5)]	200	kΩ	
CIO	Capacitance of I/O Buffer			10	pF	Fc = 1 MHz T_A = 25°C
I_{PD}	Power Down Current		20 [(5)] 10 [(5)]	50 30	µA	V_{CC} = 2.0 V to 5.5V[(3)] V_{CC} = 2.0 V to 3.3 V[(3)]
I_{CC} under RESET	Power Supply Current Maximum values, X1 mode: [(7)]			1 + 0.2 Freq (MHz) at12MHz 3.4 at16MHz 4.2	mA	V_{CC} = 3.3 V[(1)]
I_{CC} operating	Power Supply Current Maximum values, X1 mode: [(7)]			1 + 0.3 Freq (MHz) at12MHz 4.6 at16MHz 5.8	mA	V_{CC} = 3.3 V[(8)]
I_{CC} idle	Power Supply Current Maximum values, X1 mode: [(7)]			0.15 Freq (MHz) + 0.2 at12MHz 2 at16MHz 2.6	mA	V_{CC} = 3.3 V[(2)]

Notes:
1. I_{CC} under reset is measured with all output pins disconnected; XTAL1 driven with T_{CLCH}, T_{CHCL} = 5 ns (see Figure 17.), V_{IL} = V_{SS} + 0.5V,
   V_{IH} = V_{CC} - 0.5V; XTAL2 N.C.; $\overline{EA}$ = RST = Port 0 = V_{CC}. I_{CC} would be slightly higher if a crystal oscillator used..
2. Idle I_{CC} is measured with all output pins disconnected; XTAL1 driven with T_{CLCH}, T_{CHCL} = 5 ns, V_{IL} = V_{SS} + 0.5V, V_{IH} = V_{CC} - 0.5V; XTAL2 N.C; Port 0 = V_{CC}; $\overline{EA}$ = RST = V_{SS} (see Figure 15.).
3. Power Down I_{CC} is measured with all output pins disconnected; $\overline{EA}$ = V_{SS}, PORT 0 = V_{CC}; XTAL2 NC.; RST = V_{SS} (see Figure 16.).
4. Capacitance loading on Ports 0 and 2 may cause spurious noise pulses to be superimposed on the V_{OL}s of ALE and Ports 1 and 3. The noise is due to external bus capacitance discharging into the Port 0 and Port 2 pins when these pins make 1 to 0 transitions during bus operation. In the worst cases (capacitive loading 100pF), the noise pulse on the ALE line may exceed 0.45V with maxi V_{OL} peak 0.6V. A Schmitt Trigger use is not necessary.
5. Typicals are based on a limited number of samples and are not guaranteed. The values listed are at room temperature and 5V.
6. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
   Maximum I_{OL} per port pin: 10 mA
   Maximum I_{OL} per 8-bit port:

Figure 16. I_{CC} Test Condition, Power-down Mode

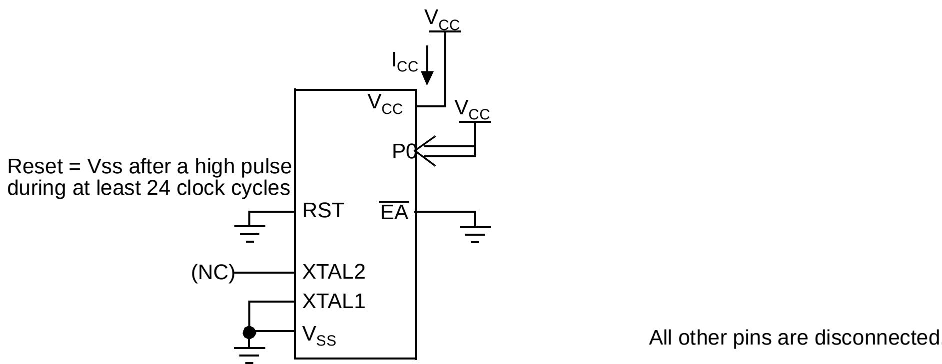
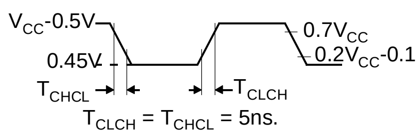


Figure 17. Clock Signal Waveform for I_{CC} Tests in Active and Idle Modes



AC Parameters

Explanation of the AC Symbols

Each timing symbol has 5 characters. The first character is always a "T" (stands for time). The other characters, depending on their positions, stand for the name of a signal or the logical status of that signal. The following is a list of all the characters and what they stand for.

Example: T_{AVLL} = Time for Address Valid to ALE Low.
T_{LLPL} = Time for ALE Low to $\overline{PSEN}$ Low.

T_A = 0 to +70°C (commercial temperature range); V_{SS} = 0 V; V_{CC} = 5V ± 10%; -M and -V ranges.
T_A = -40°C to +85°C (industrial temperature range); V_{SS} = 0 V; V_{CC} = 5V ± 10%; -M and -V ranges.
T_A = 0 to +70°C (commercial temperature range); V_{SS} = 0 V; 2.7 V < V_{CC} < 5.5V; -L range.
T_A = -40°C to +85°C (industrial temperature range); V_{SS} = 0 V; 2.7 V < V_{CC} < 5.5V; -L range.

Table 24. gives the maximum applicable load capacitance for Port 0, Port 1, 2 and 3, and ALE and $\overline{PSEN}$ signals. Timings will be guaranteed if these capacitances are respected. Higher capacitance values can be used, but timings will then be degraded.

Table 24. Load Capacitance versus speed range, in pF

	-M	-V	-L
Port 0	100	50	100
Port 1, 2, 3	80	50	80
ALE / $\overline{PSEN}$	100	30	100

Table 5., Table 29. and Table 32. give the description of each AC symbols.

Table 27., Table 30. and Table 33. give for each range the AC parameter.

Table 27. AC Parameters for Fix Clock

Speed	-M 40 MHz		-V X2 mode 30 MHz 60 MHz equiv.		-V standard mode 40 MHz		-L X2 mode 20 MHz 40 MHz equiv.		-L standard mode 30 MHz		Units
Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
T	25		33		25		50		33		ns
T_{LHLL}	40		25		42		35		52		ns
T_{AVLL}	10		4		12		5		13		ns
T_{LLAX}	10		4		12		5		13		ns
T_{LLIV}		70		45		78		65		98	ns
T_{LLPL}	15		9		17		10		18		ns
T_{PLPH}	55		35		60		50		75		ns
T_{PLIV}		35		25		50		30		55	ns
T_{PXIX}	0		0		0		0		0		ns
T_{PXIZ}		18		12		20		10		18	ns
T_{AVIV}		85		53		95		80		122	ns
T_{PLAZ}		10		10		10		10		10	ns

Table 28. AC Parameters for a Variable Clock: derating formula

Symbol	Type	Standard Clock	X2 Clock	-M	-V	-L	Units
T_{LHLL}	Min	2 T - x	T - x	10	8	15	ns
T_{AVLL}	Min	T - x	0.5 T - x	15	13	20	ns
T_{LLAX}	Min	T - x	0.5 T - x	15	13	20	ns
T_{LLIV}	Max	4 T - x	2 T - x	30	22	35	ns
T_{LLPL}	Min	T - x	0.5 T - x	10	8	15	ns
T_{PLPH}	Min	3 T - x	1.5 T - x	20	15	25	ns
T_{PLIV}	Max	3 T - x	1.5 T - x	40	25	45	ns
T_{PXIX}	Min	x	x	0	0	0	ns
T_{PXIZ}	Max	T - x	0.5 T - x	7	5	15	ns
T_{AVIV}	Max	5 T - x	2.5 T - x	40	30	45	ns
T_{PLAZ}	Max	x	x	10	10	10	ns

Table 30. AC Parameters for a Fix Clock

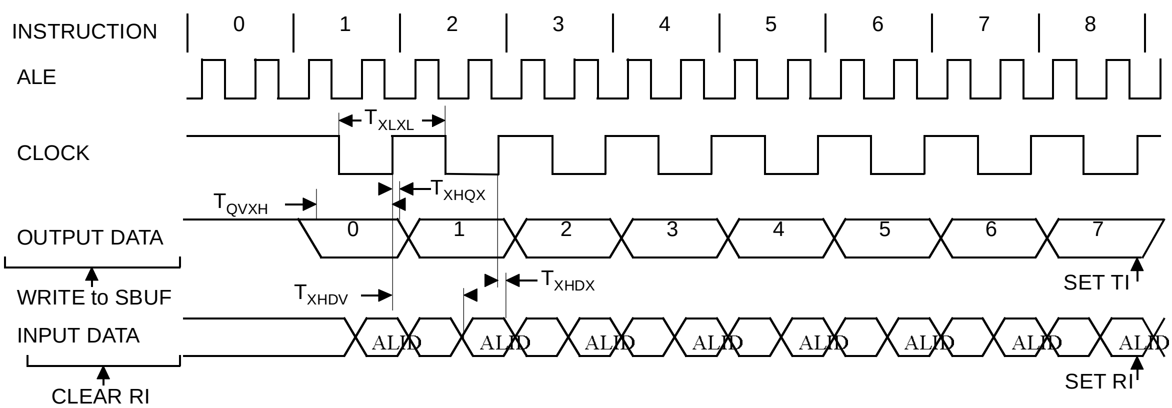
Speed	-M 40 MHz		-V X2 mode 30 MHz 60 MHz equiv.		-V standard mode 40 MHz		-L X2 mode 20 MHz 40 MHz equiv.		-L standard mode 30 MHz		Units
Symbol	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	
T_{RLRH}	130		85		135		125		175		ns
T_{WLWH}	130		85		135		125		175		ns
T_{RLDV}		100		60		102		95		137	ns
T_{RHDX}	0		0		0		0		0		ns
T_{RHDZ}		30		18		35		25		42	ns
T_{LLDV}		160		98		165		155		222	ns
T_{AVDV}		165		100		175		160		235	ns
T_{LLWL}	50	100	30	70	55	95	45	105	70	130	ns
T_{AVWL}	75		47		80		70		103		ns
T_{QVWX}	10		7		15		5		13		ns
T_{QVWH}	160		107		165		155		213		ns
T_{WHQX}	15		9		17		10		18		ns
T_{RLAZ}		0		0		0		0		0	ns
T_{WHLH}	10	40	7	27	15	35	5	45	13	53	ns

Table 34. AC Parameters for a Variable Clock: Derating Formula

Symbol	Type	Standard Clock	X2 Clock	-M	-V	-L	Units
T_{XLXL}	Min	12 T	6 T				ns
T_{QVHX}	Min	10 T - x	5 T - x	50	50	50	ns
T_{XHQX}	Min	2 T - x	T - x	20	20	20	ns
T_{XHDX}	Min	x	x	0	0	0	ns
T_{XHDV}	Max	10 T - x	5 T- x	133	133	133	ns

Shift Register Timing Waveforms

Figure 21. Shift Register Timing Waveforms



Ordering Information

Table 37. Possible Ordering Entries

Part Number[3]	Memory Size	Supply Voltage	Temperature Range	Max Frequency	Package	Packing
TS80C32X2-MCA	ROMLess	5V ±10%	Commercial	40 MHz[1]	PDIL40	Stick
TS80C32X2-MCB	ROMLess	5V ±10%	Commercial	40 MHz[1]	PLCC44	Stick
TS80C32X2-MCC	ROMLess	5V ±10%	Commercial	40 MHz[1]	PQFP44	Tray
TS80C32X2-MCE	ROMLess	5V ±10%	Commercial	40 MHz[1]	VQFP44	Tray
TS80C32X2-LCA	ROMLess	2.7 to 5.5V	Commercial	30 MHz[1]	PDIL40	Stick
TS80C32X2-LCB	ROMLess	2.7 to 5.5V	Commercial	30 MHz[1]	PLCC44	Stick
TS80C32X2-LCC	ROMLess	2.7 to 5.5V	Commercial	30 MHz[1]	PQFP44	Tray
TS80C32X2-LCE	ROMLess	2.7 to 5.5V	Commercial	30 MHz[1]	VQFP44	Tray
TS80C32X2-VCA	ROMLess	5V ±10%	Commercial	60 MHz[3]	PDIL40	Stick
TS80C32X2-VCB	ROMLess	5V ±10%	Commercial	60 MHz[3]	PLCC44	Stick
TS80C32X2-VCC	ROMLess	5V ±10%	Commercial	60 MHz[3]	PQFP44	Tray
TS80C32X2-VCE	ROMLess	5V ±10%	Commercial	60 MHz[3]	VQFP44	Tray
TS80C32X2-MIA	ROMLess	5V ±10%	Industrial	40 MHz[1]	PDIL40	Stick
TS80C32X2-MIB	ROMLess	5V ±10%	Industrial	40 MHz[1]	PLCC44	Stick
TS80C32X2-MIC	ROMLess	5V ±10%	Industrial	40 MHz[1]	PQFP44	Tray
TS80C32X2-MIE	ROMLess	5V ±10%	Industrial	40 MHz[1]	VQFP44	Tray
TS80C32X2-LIA	ROMLess	2.7 to 5.5V	Industrial	30 MHz[1]	PDIL40	Stick
TS80C32X2-LIB	ROMLess	2.7 to 5.5V	Industrial	30 MHz[1]	PLCC44	Stick
TS80C32X2-LIC	ROMLess	2.7 to 5.5V	Industrial	30 MHz[1]	PQFP44	Tray
TS80C32X2-LIE	ROMLess	2.7 to 5.5V	Industrial	30 MHz[1]	VQFP44	Tray
TS80C32X2-VIA	ROMLess	5V ±10%	Industrial	60 MHz[3]	PDIL40	Stick
TS80C32X2-VIB	ROMLess	5V ±10%	Industrial	60 MHz[3]	PLCC44	Stick
TS80C32X2-VIC	ROMLess	5V ±10%	Industrial	60 MHz[3]	PQFP44	Tray
TS80C32X2-VIE	ROMLess	5V ±10%	Industrial	60 MHz[3]	VQFP44	Tray
AT80C32X2-3CSUM	ROMLess	5V ±10%	Industrial & Green	40 MHz[1]	PDIL40	Stick
AT80C32X2-SLSUM	ROMLess	5V ±10%	Industrial & Green	40 MHz[1]	PLCC44	Stick
AT80C32X2-RLTUM	ROMLess	5V ±10%	Industrial & Green	40 MHz[1]	VQFP44	Tray
AT80C32X2-RLTUM	ROMLess	5V ±10%	Industrial & Green	40 MHz[1]	VQFP44	Tape & Reel
AT80C32X2-3CSUL	ROMLess	2.7 to 5.5V	Industrial & Green	30 MHz[1]	PDIL40	Stick
AT80C32X2-SLSUL	ROMLess	2.7 to 5.5V	Industrial & Green	30 MHz[1]	PLCC44	Stick

Table 37. Possible Ordering Entries (Continued)

Part Number(3)	Memory Size	Supply Voltage	Temperature Range	Max Frequency	Package	Packing
AT80C52X2zzz-3CSUL	8K ROM	2.7 to 5.5V	Industrial & Green	30 MHz(1)	PDIL40	Stick
AT80C52X2zzz-SLSUL	8K ROM	2.7 to 5.5V	Industrial & Green	30 MHz(1)	PLCC44	Stick
AT80C52X2zzz-RLTUL	8K ROM	2.7 to 5.5V	Industrial & Green	30 MHz(1)	VQFP44	Tray
AT80C52X2zzz-3CSUV	8K ROM	5V ±10%	Industrial & Green	60 MHz(3)	PDIL40	Stick
AT80C52X2zzz-SLSUV	8K ROM	5V ±10%	Industrial & Green	60 MHz(3)	PLCC44	Stick
AT80C52X2zzz-RLTUV	8K ROM	5V ±10%	Industrial & Green	60 MHz(3)	VQFP44	Tray
TS87C52X2-MCA	8K OTP	5V ±10%	Commercial	40 MHz(1)	PDIL40	Stick
TS87C52X2-MCB	8K OTP	5V ±10%	Commercial	40 MHz(1)	PLCC44	Stick
TS87C52X2-MCC	8K OTP	5V ±10%	Commercial	40 MHz(1)	PQFP44	Tray
TS87C52X2-MCE	8K OTP	5V ±10%	Commercial	40 MHz(1)	VQFP44	Tray
TS87C52X2-LCA	8K OTP	2.7 to 5.5V	Commercial	30 MHz(1)	PDIL40	Stick
TS87C52X2-LCB	8K OTP	2.7 to 5.5V	Commercial	30 MHz(1)	PLC44	Stick
TS87C52X2-LCC	8K OTP	2.7 to 5.5V	Commercial	30 MHz(1)	PQFP44	Tray
TS87C52X2-LCE	8K OTP	2.7 to 5.5V	Commercial	30 MHz(1)	VQFP44	Tray
TS87C52X2-VCA	8K OTP	5V ±10%	Commercial	60 MHz(3)	PDIL40	Stick
TS87C52X2-VCB	8K OTP	5V ±10%	Commercial	60 MHz(3)	PLCC44	Stick
TS87C52X2-VCC	8K OTP	5V ±10%	Commercial	60 MHz(3)	PQFP44	Tray
TS87C52X2-VCE	8K OTP	5V ±10%	Commercial	60 MHz(3)	VQFP44	Tray
TS87C52X2-MIA	8K OTP	5V ±10%	Industrial	40 MHz(1)	PDIL40	Stick
TS87C52X2-MIB	8K OTP	5V ±10%	Industrial	40 MHz(1)	PLCC44	Stick
TS87C52X2-MIC	8K OTP	5V ±10%	Industrial	40 MHz(1)	PQFP44	Tray
TS87C52X2-MIE	8K OTP	5V ±10%	Industrial	40 MHz(1)	VQFP44	Tray
TS87C52X2-LIA	8K OTP	2.7 to 5.5V	Industrial	30 MHz(1)	PDIL40	Stick
TS87C52X2-LIB	8K OTP	2.7 to 5.5V	Industrial	30 MHz(1)	PLCC44	Stick
TS87C52X2-LIC	8K OTP	2.7 to 5.5V	Industrial	30 MHz(1)	PQFP44	Tray
TS87C52X2-LIE	8K OTP	2.7 to 5.5V	Industrial	30 MHz(1)	VQFP44	Tray
TS87C52X2-VIA	8K OTP	5V ±10%	Industrial	60 MHz(3)	PDIL40	Stick
TS87C52X2-VIB	8K OTP	5V ±10%	Industrial	60 MHz(3)	PLCC44	Stick
TS87C52X2-VIC	8K OTP	5V ±10%	Industrial	60 MHz(3)	PQFP44	Tray
TS87C52X2-VIE	8K OTP	5V ±10%	Industrial	60 MHz(3)	VQFP44	Tray

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